

PMP8380_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	0.1uF	Capacitor, Ceramic, 250V, X7R, 15%	1206	STD	STD
1	C10	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C101	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	0603	STD	STD
1	C102	0.47uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C11	100uF	Capacitor, Aluminum, 25V, ±20%	0.260 x 0.276 inch	EEVFK1E101XP	Panasonic
3	C12, C13, C17	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
2	C14, C25	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C15	100pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C16	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
6	C18, C19, C20, C21, C22, C24	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	STD	STD
2	C2, C3	10pF	Capacitor, Ceramic, 100V, C0G, 10%	0603	STD	STD
1	C23	47uF	CAP ELECT 47UF 80V FK SMD	0.457 x 0.406	EEE-FK1K470P	Panasonic
1	C4	470uF	CAP ELECT 470UF 16V HC SMD	0.457 x 0.406	EEE-HC1C471P	Panasonic
1	C5	1000pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
1	C6	3300pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
3	C7, C8, C100	47uF	Capacitor, Ceramic, 16V, X5R, 15%	1210	STD	STD
1	C9	4.7uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
2	D1, D2	8.2V	Diode, Zener, 8.2-V, -225-mW	SOT23	MMBZ5237BLT1	ON Semi
1	D100	MURA120T3	Diode, UltraFast Rectifier, 1-A, 200-V	403A	MURA120T3	On Semi
1	D5	BAV99	Diode, Dual Ultra Fast, Series, 200-mA, 70-V	SOT23	BAV99	Fairchild
4	D6, D7, D101, D102	BAV21W	DIODE SWITCH 200V 250MW SOD123	SOD-123	BAV21W-7-F	Diodes Inc.
1	D8	MMSD914T1	Diode, Switching, 100-V, 200-mA, 225-mW,	SOD-123	MMSD914T1	On Semi
4	J1, J2, J3, J4	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L1	6uH	Inductor, SMT, 14.4A, 4.4milliohm	0.750 x 0.875 inch	PA2729.602NL	Pulse
1	L2	1mH	Inductor, SMT, 110mA, 13.8ohm	0.26x0.09 inch	DO1608C-105ML	Coilcraft
1	L3	10uH	Inductor, SMT, 8.6A, 11milliohm	0.600 x 0.710 inch	DO5040H-103ML	Coilcraft
4	Q1, Q2, Q4, Q5	FDMS86200	MOSFET N-CH 150V POWER56	TDSON-8	FDMS86200	Fairchild
1	Q10	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
3	Q11, Q100, Q101	MMBT2907A	Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi
1	Q3	IRF6216PBF	MOSFET, PChan, -150V, -2.2A, 0.24 Ohm	SO8	IRF6216PBF	IR
2	Q6, Q7	SI7852ADP	MOSFET N-CH 80V 30A PPAK 8SOIC	TDSON-8	SI7852ADP	Vishay
2	Q8, Q9	FZT655	TRANS NPN HP 150V 1000MA SOT-223	SOT223	FZT655TA	Diodes Inc.
2	R1, R103	0.02	Resistor, Metal Oxide, 1W, 5%	2512	STD	STD
1	R10	78.7k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R101	15k	Resistor, Metal Oxide, 1W, 5%	2512	STD	STD
1	R12	60.4k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R13, R100	2k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R14	2.61k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R16, R18	0	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R17	4.70k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R2	4k	Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
1	R20	1	Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
1	R3	2.49k	Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
2	R4, R9	100k	Resistor, Chip, 1/16W, 1%	0603	STD	STD

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3	R5, R11, R15	10k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
3	R6, R8, R102	1k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R7	49.9k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	T2	75uH	Transformer, High Frequency Planar, 2 Prim, 2 Sec.	0.950 x 0.790 inch	PA0801.004	Pulse
3	TP1, TP2, TP4	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP3, TP5	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	TI
1	U3	TL431DBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431DBZ	TI
1	U4	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay

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